Product information



FEATURES:

- · Easy to install and use
- Fast treatment times
- · Vacuum level
- · Process gas
- · Process control
- Cost efficient surface treatment

VacuTEC 5050 Vacuum Plasma Treater

Standard Vacuum Plasma Treater







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Tantecs VacuTEC 5050 Plasma Treater is designed for treatment of a large number of different injection moulded parts. The VacuTEC offers very fast treatment times and optimum adhesion properties for downstream coating, gluing, painting and printing applications.

In the treating chamber a vacuum is built up to between 0,1 and 3 mbar before an electrical discharge is created through the integrated plasma electrode. Treatment cycle times are often short, between 5 - 600 seconds depending on the material and its formulation.

Effective size for products on 2 shelves: $500 \times 500 \times 100$ mm.

The VacuTEC is appreciated for its simplicity of operation, reliability in production and fast process speed. Treating gasses such as argon and oxygen can be applied, but in most cases this is not necessary due to the high power exposed by the plasma discharge.

VacuTEC uses the advanced Tantec power generator HV-X series as power supply and specially designed plasma transformer to provide voltage to the plasma electrodes.

Tantec has both standard VacuTEC machines, but also custom-designed machines. The VacuTEC customized machines are specially developed and adapted 100% to customer wishes and requirements in relation to the production line.

Technical Data



Easy to install and use

Connect to mains power.

Fast treatment times

High power impact enables treatment times from 5 - 600 seconds, depending on material.

Vacuum level

The plasma discharge is active from 0,1 - 3 mbar depending on application.

Process gas

Process gasses such as oxygen and argon can be used, but in most cases it is not necessary.

Process control

The entire plasma process is controlled by the HV-X generator and the PLC unit.

All parameters are displayed through the touch panel.

Cost efficient surface treatment

Due to low power consumption and no need of special treatment gasses the unit is a very cost efficient solution for improving surface wettability and adhesion.

Vacuum pressure Plasma

Enables treatment of both conductive and non-conductive surfaces.

Chamber door

Hinged door with window and safety switch.

Technical Specifications	VacuTEC 5050 Vacuum Plasma Treater
Mains Voltage and Frequency	100-480 VAC 50/60 Hz
Output voltage/plasma power	5kV / 1000W
Power source	HV-X10 generator
Compressed air inlet	6 bar dry & clean
Treatment gas	Standard air, oxygen, argon, nitrogen on request
Vacuum pump capacity in m³/min.	100m³/hour
Vacuum level	0,1 — 3 mbar
Evacuation time, typical	90 sec.
Plasma treatment time, typical	5 – 600 seconds, depending on material
Control and connectivity	Complete with Tantec touch panel.
Regulation compliance	CE - RoHS - WEEE
Dimensions	1115 x 955 x 1745 mm
Shelves:	2
Tray size	500 x 500 x 100 mm